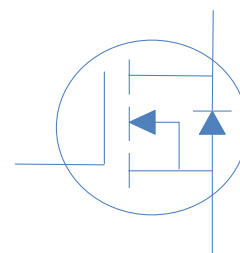


150V N-Ch Power MOSFET

V_{DS}	150	V
$R_{DS(on),typ}$	3.8	m
I_D (Silicon Limited)	239	A



Part Number	Package	Marking
HGT041N15S	TOLL	GT041N15S

Absolute Maximum Ratings at $T_j = 0^\circ\text{C}$

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C = 0^\circ\text{C}$	239	A
		$T_C = 100^\circ\text{C}$	128	
Drain to Source Voltage	V_{DS}	-	150	V
Gate to Source Voltage	V_{GS}	-	20	V
Pulsed Drain Current	I_{DM}	-	800	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4\text{mH}, T_C = 0^\circ\text{C}$	720	mJ
Power Dissipation	P_D	$T_C = 0^\circ\text{C}$	600	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\theta JA}$	0.25	
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	60	



Drain to Source Breakdown Voltage

typ	max
-	4
-	1
-	100

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

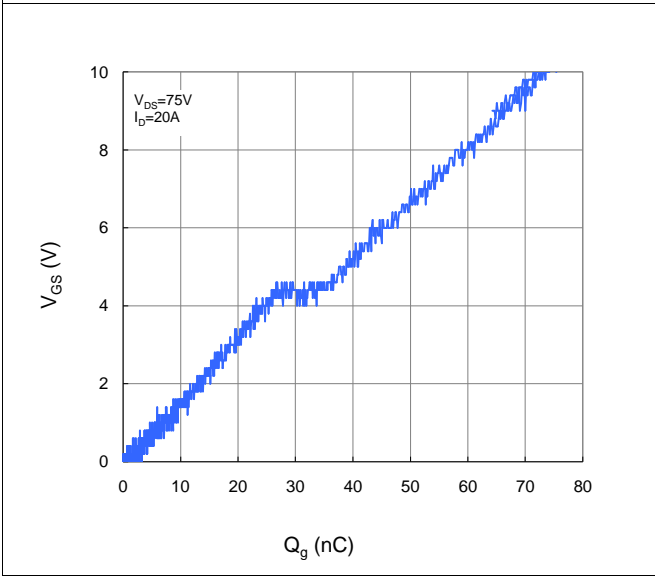


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

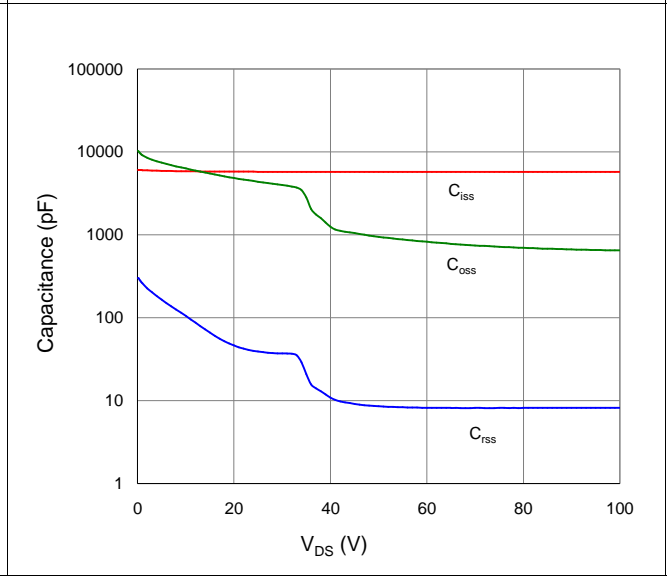


Figure 9. Maximum Safe Operating Area

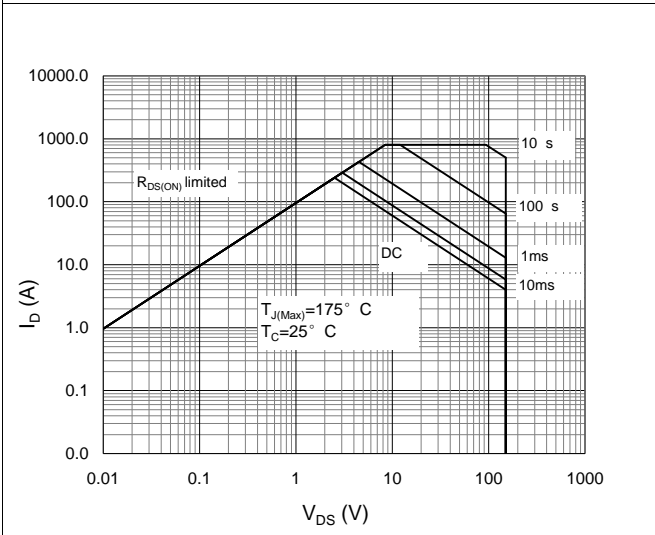


Figure 10. Maximum Drain Current vs. Case Temperature

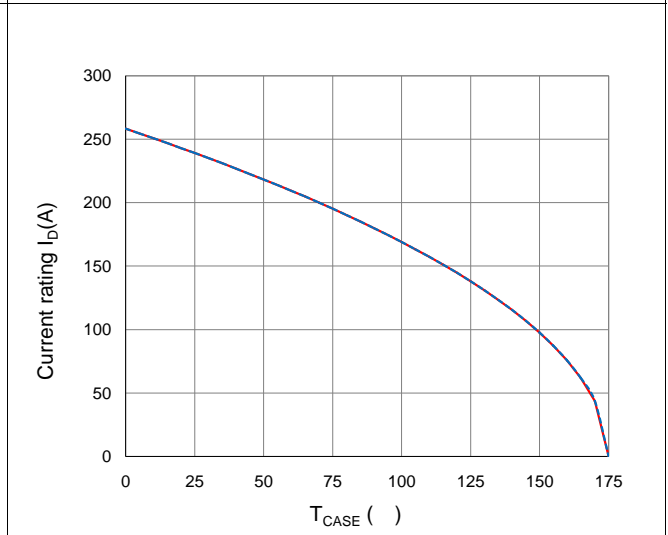
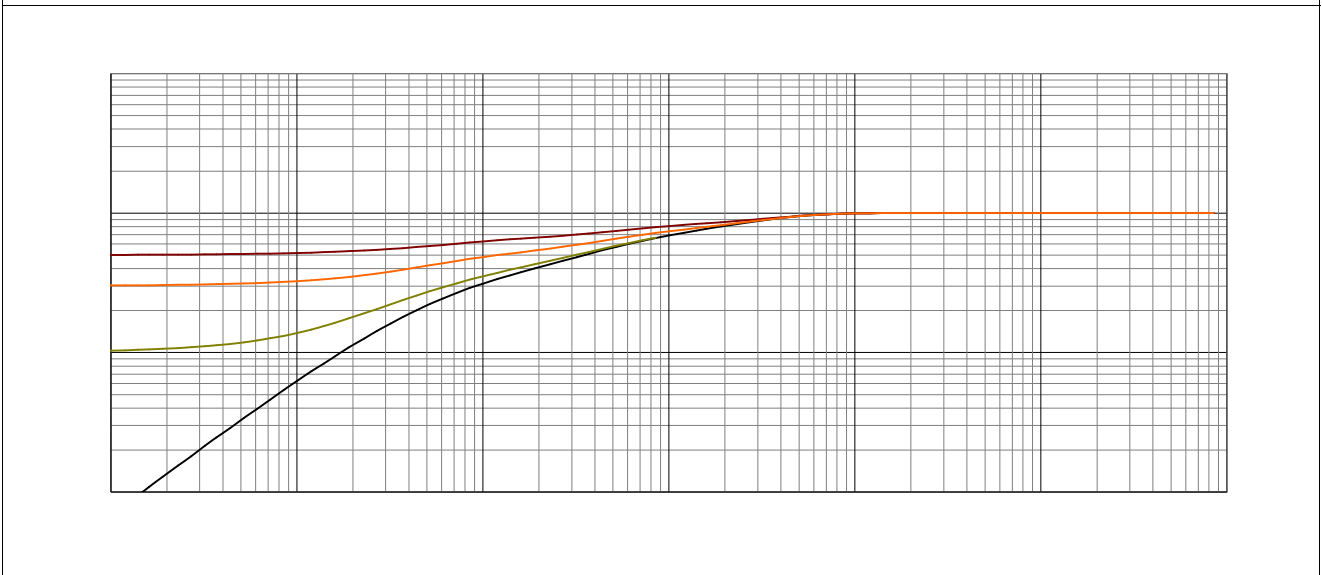
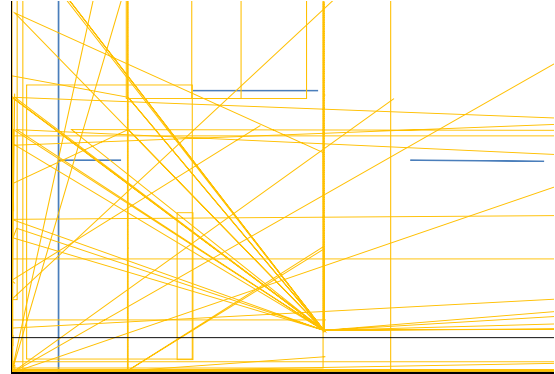
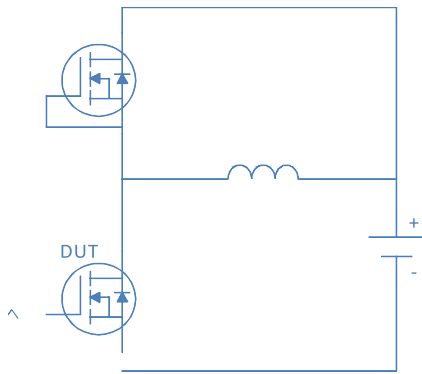


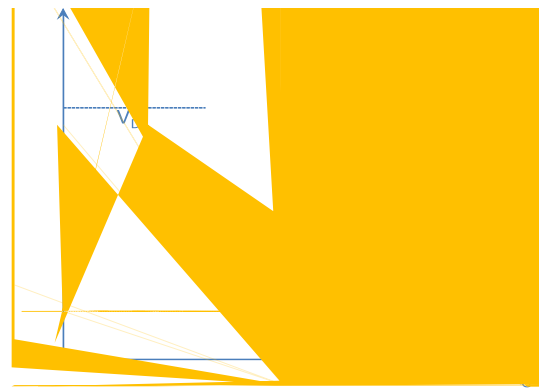
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



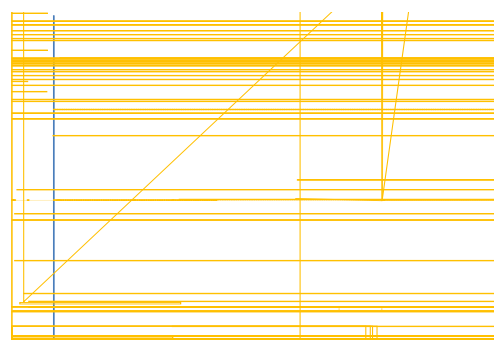
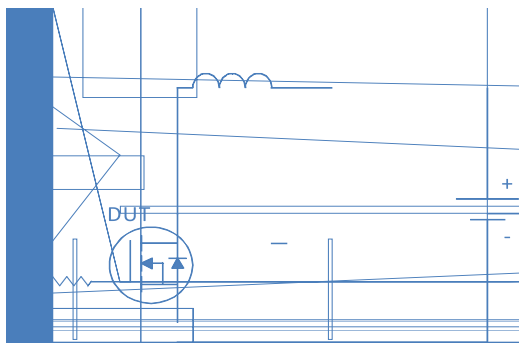
Inductive switching Test



Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test

